

TITLE OF THE INVENTION: ELECTRONIC DEVICE AND A METHOD FOR FORMING THE SAME

Abstract

An electronic device is provided, wherein the electronic device comprises: a package substrate; two interposers disposed on the package substrate; an electronic component mounted on the two interposers to be electrically coupled to the package substrate via the two interposers; a mold cap formed on the package substrate to encapsulate the two interposers and expose the electronic component, wherein the mold cap comprises two sets of interconnects extending therethrough and each being electrically coupled to one of the interposers; two semiconductor dice mounted on the mold cap and the electronic component to form a gap between the two semiconductor dice and above the electronic component, wherein each of the two semiconductor dice is electrically coupled to one of the two interposers via one set of the two sets of interconnects; and a heat spreader attached on and thermally coupled to the two semiconductor dice and the electronic component.

[FIG. 1E]